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PATENT APPLICATION
[Handwritten signature] 068028

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Tomoo MURAKAMI

Divisional of Appln. No. 09/120,204
Filed: July 22, 1998

Group Art Unit: 3729
Examiner: L. Young

Appln. No.: Not yet assigned
Filed: January 16, 2002

Group Art Unit: not yet assigned

For: METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND
A MOUNTED STRUCTURE

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Amend the specification by inserting before the first line the sentence:

AI
This is a divisional of Application No. 09/120,204 filed July 22, 1998; the disclosure of
which is incorporated herein by reference.

**Page 1, fourth paragraph, which bridges to page 2, please delete and insert the
following new paragraph:**

AD
Referring to Fig. 1, an insulating resin layer 2 made of a material such as rubber having
elastic recovery force is formed on a substrate 1. Further, a mounting pad 3 is formed on the
insulating resin layer 2 by means of sputtering or vapor deposition. A sealing resin 5 is coated to